LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司

Winstar Display Co., LTD 華凌光電股份有限公司



WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

CUSTOMER :	~ ()
MODULE NO.:	WO240128B-TFH#

APPROVED	BY:
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(FOR CUSTOMER USE ONLY)

PCB VERSION:

DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY	
F	2023/01/18		Modify Information	Backlight (Note)



MODLE NO:

華凌光電股份有限公司

RECORDS OF REVISION

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.		SUMMARY
0	2016/07/25		Fir	rst issue
A	2016/11/04		Mo	odify IDD.
В	2017/06/23		Co	orrect FPC.
C	2019/08/27		Mo	odify Material List of
			Co	omponents for RoHs
D	2019/12/17			odify Precautions in use
		(C	of	LCD Modules
E	2021/01/04		Ac	ld Interface
F	2023/01/18		Mo	odify Backlight
			Inf	Formation(Note)

Contents

- 1.Module Classification Information
- 2.Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13.Recommendable Storage
- 14.Initial code

1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 240 * 128 dot

Model serials no.

© Backlight Type: N \rightarrow Without backlight T \rightarrow LED, White L \rightarrow LED, Full color

 $B\rightarrow EL$, Blue green $A\rightarrow LED$, Amber $J\rightarrow DIP$ LED, Blue $D\rightarrow EL$, Green $R\rightarrow LED$, Red $K\rightarrow DIP$ LED, White

W→EL, White O→LED, Orange E→DIP LED, Yellow Green

 $M\rightarrow EL$, Yellow Green $G\rightarrow LED$, Green $H\rightarrow DIP$ LED, Amber $F\rightarrow CCFL$, White $P\rightarrow LED$, Blue $I\rightarrow DIP$ LED, Red

 $Y\rightarrow$ LED, Yellow Green $X\rightarrow$ LED, Dual color $G\rightarrow$ LED, Green $C\rightarrow$ LED, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00 I→Transmissive, W.T, 6:00 I→Tra

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

3.General Specification

Item	Dimension	Unit
Number of dots	240 x 128	_
Module dimension	122.2 x 79.8 x 6.5	mm
View area	114.0 x 64.0	mm
Active area	107.98 x 57.58	mm
Dot size	0.43 x 0.43	mm
Dot pitch	0.45 x 0.45	mm
LCD type	FSTN Positive Transflective (In LCD production, It will occur slightly color of can only guarantee the same color in the same based on the same based of the same based on the	
Drive Method	1/128D · 1/12B	
View direction	6 o'clock	
Backlight Type	LED, White	
IC	ST7586S	
Interface	68 series /80 series /3 Line/4 Line	

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	$^{\circ}$ C
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Digital Power Supply Voltage	VDDI	-0.3	_	3.6	V
Analog Power supply voltage	VDDA	-0.3	_	3.6	V
LCD Power supply voltage	V0-XV0	-0.3	_	19	V
LCD Power supply voltage	VG	-0.3	7	5.5	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	3.0	3.3	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	VOP	Ta=25°℃	14.8	15.0	15.2	V
		Ta=+70°C	_	_		V
Input High Volt.	$V_{ m IH}$	_	$0.7V_{DD}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	Vss	~(0.3 V _{DD}	V
Output High Volt.	V_{OH}	_	$0.8\mathrm{V}_\mathrm{DD}$		V_{DD}	V
Output Low Volt.	V_{OL}	-	Vss	_	$0.2V_{\mathrm{DD}}$	V
Supply Current	I_{DD}	V _{DD} =3.3V		2.0	4.0	mA

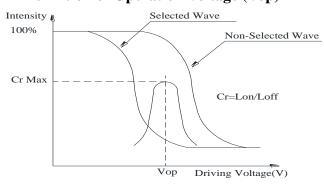
Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

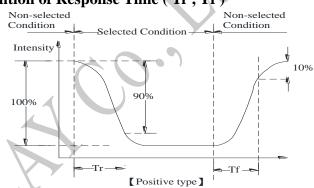
6.Optical Characteristics

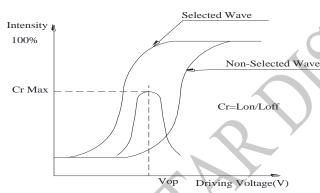
Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR≧2	0	_	30	$\phi = 180^{\circ}$
	θ	CR≧2	0	_	60	$\phi = 0^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	_	250	350	ms

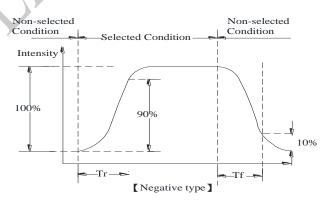
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)









Conditions:

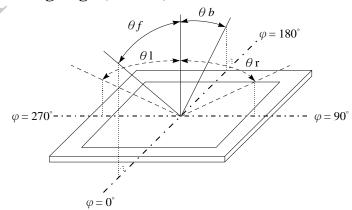
Operating Voltage: Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency: 64 HZ Driving

Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle $(CR \ge 2)$

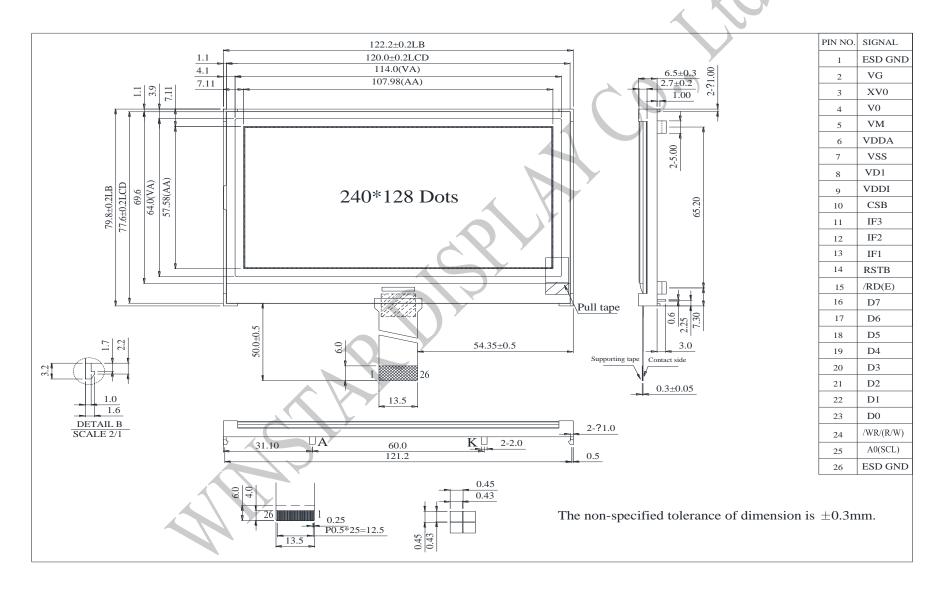


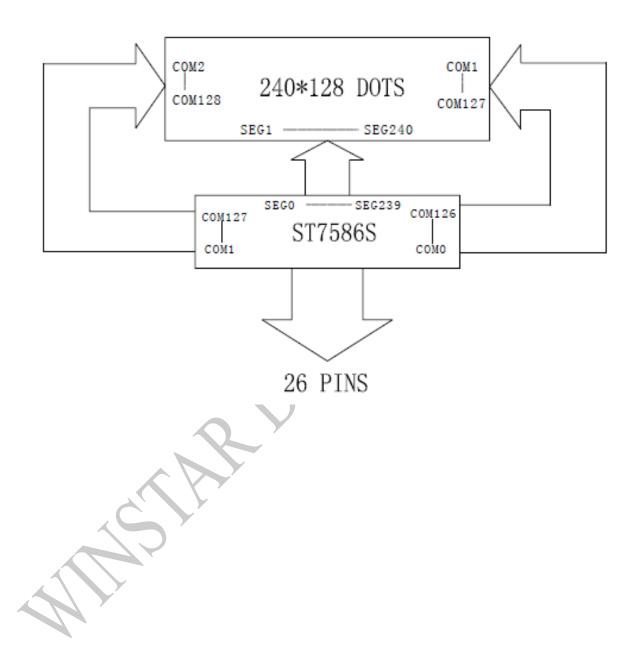
7.Interface Pin Function

Pin No.	Symbol	Description						
1	ESD GND	lectro-Static discharge						
2	VG	VG is the power of SEG-drivers						
3	XV0	Negative operating voltage of COM-drivers						
4	V0	Positive operating voltage of COM-drivers						
5	VM	VM is the non-select voltage level of COM-drivers						
6	VDDA	Power supply						
7	VSS	Ground						
8	VD1	Digital power source selection						
9	VDDI	VDD1 is the power of interface I/O circuit						
10	CSB	Chip select input pin CSB="L": This chip is selected and the MPU interface is active CSB="H": This chip is not selected and the MPU interface is disabled (D[7:0] are high impedance)						
11	IF3	These pins select interface operation mode						
12	IF2	IF3 IF2 IF1 MPU interface type						
14	RSTB	Reset input pin. When RSTB is "L", internal initialization procedure is executed						
		Read / Write execution control pin. (This pin is only used in parallelinterface)						
15	/RD(E)	MPU Type ERD Description Read / Write control input pin. R/W = "H": When E is "H", data bus is in output status. R/W = "L": The data are latched at the falling edge of the E signal.						
		8080-series /RD Read enable input pin. When /RD is "L", data bus is in output status.						
		This pin is not used in serial interfaces and should be connected to VDD1						

16~23	D7~D0	The bi-directional data bus of the MPU interface. When CSB is "H", they are high mpedance if using serial interface: Do is the SDA signal in 4-Line & 3-Line interface Do is the AO signal in 4-Line interface				
				control pin. (This pin is only used in parallel inter	face)	
		MPU Type	RWR	Description]	
				Read / Write control input pin		
24	/WR/(R/W)	6800-series R	R/W	R/W = "H" : read	7	
2 1	, , , , ,			R/W = "L" : write]	
		8080-series	WR	Write enable clock input pin.		
				The data are latched at the rising edge of the /WR signal.]	
		This pin is not used in serial interfaces and should be connected to VDD1				
		The function of	thia nin	is different in parallel and serial interface		
			-	•		
		In parallel interface: A0 is register selection input				
25	A0(SCL)	A0 = "H": inpu	ts on dat	ta bus are display data		
		A0 = "L": inputs on data bus are command				
		In serial interface: this pad will be used as SCL (serial-clock) input				
26	ESD GND	Electro-Static d	lischarge			

8.Contour Drawing & Block Diagram





9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Not e
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 96hrs ▲	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 96hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 96hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 96hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90% RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= ± 600 V(contact), ± 800 v(air), RS= 330Ω CS= 150 pF 10 times	

Note1: No dew condensation to be observed.

Note 2: The function test shall be conducted after 4 hours storage at the normal ${\bf r}$

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

10.Backlight Information

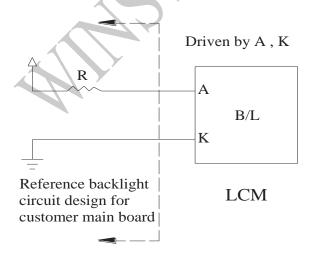
Specification

Parameter Parameter	Symbol	Min	Тур	Max	Unit	Test Condition
Supply Current	ILED	_	144	180	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	-
Reverse Voltage	VR	_	_	5	V	- XO
	X	0.244	0.264	0.284		
Color coordinate	Y	0.264	0.284	0.304		ILED=144mA
Luminance	TX 7	750	0.40		4, 2	W. T. 144
(Without LCD)	IV	750	940	_	cd/m ²	ILED=144mA
					> ,	ILED=144mA
LED Life Time	_	_	50K		Hr.	25°C,50-60%RH,
(For Reference only)			(4)	Y		(Note 1)
Color	White					

Note: A backlight driven by voltage will keep the drive current under the safe area (current between minimum and maximum).

If the B/L LED is driven by current only, the drive voltage cannot be considered as a reference value.

Note 1:50K hours is only an estimate for reference.



11.Inspection specification

No	Item			Criterion		AQL
		Missing vertical,	horizont	al segment, segment	t contrast defect.	
		Missing characte	er, dot or	icon.		
		Display malfunc	tion.			
01	Electrical	No function or no	o display.	•		0.65
01	Testing	Current consump	otion exce	eeds product specific	cations.	0.03
		LCD viewing an	gle defec	t.		
		Mixed product ty	ypes.			V
		Contrast defect.				
	Black or white	2.1 White and bl	ack spots	on display $\leq 0.25 \text{m}$	nm, no more than	
02	spots on LCD	three white or bla	ack spots	present.		2.5
	(display only)	2.2 Densely space	ed: No m	nore than two spots of	or lines within 3mm	
		3.1 Round type:	As follow	wing drawing		
		$\Phi = (x + y) / 2$				
		X	. [Size	Acceptable QTY	
				Φ≦0.10	Accept no dense	2.5
		7	F 1	$0.10 < \Phi \le 0.20$	2	
	LCD black spots,			$0.20 < \Phi \le 0.25$	1	
03	white spots, contamination			0.25 < Ф	0	
	(non-display)	3.2 Line type : (A	As follow	ing drawing)	<u> </u>	
	1 3/	A Y	Length	Width	Acceptable Q TY	
		_ /¥ w		W≦0.02	Accept no dense	
		→ ; H—	L≦3.0	$0.02 < W \le 0.03$		2.5
		12.	L≦2.5	$0.03 < W \le 0.05$	2	
				0.05 < W	As round type	
		If bubbles are vis	sible,	Size Φ	Acceptable Q TY	
	M	judge using black	k spot	$\Phi \leq 0.20$	Accept no dense	
04	Polarizer bubbles	specifications, no	ot easy	$0.20 < \Phi \leq 0.50$	3	2.5
		to find, must che	ck in	$0.50 < \Phi \le 1.00$	2	
		specify direction		1.00<Ф	0	
				Total Q TY	3	

No	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD blac	k spots, white spots, cor	ntamination	
0.5	Scratches	Symbols Define: x: Chip length y: k: Seal width t: L: Electrode pad length 6.1 General glass chip:	Chip width z: Chi Glass thickness a: LC	ip thickness D side length	
		z: Chip thickness	y: Chip width	x: Chip length	
	Chipped	Z≦1/2t	Not over viewing area	x ≤ 1/8a	
06	glass	$1/2t < z \leq 2t$	Not exceed 1/3k	x ≤ 1/8a	2.5
		⊙ If there are 2 or more 6.1.2 Corner crack:	chips, x is total length o	of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≤1/2t	Not over viewing area	x ≤ 1/8a	
	1	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
		⊙ If there are 2 or more	chips, x is the total leng	gth of each chip.	

No	Item			Criter	ion		AQL
		Symbols:					
		x: Chip length	y: Chip w	idth	z: Chi	p thickness	
		k: Seal width	t: Glass th	ickness	a: LCl	D side length	
		L: Electrode pad len	gth				
		6.2 Protrusion over	terminal:				
		6.2.1 Chip on electro	ode pad:				
		y: Chip width $y \le 0.5 \text{mm}$ 6.2.2 Non-conductive		$\begin{array}{c} L \\ \hline Chip leng \\ \hline x \leq 1/8a \\ \hline L \\ \hline \end{array}$	Z gth	$\begin{array}{c c} \textbf{z: Chip thickness} \\ 0 < \textbf{z} \leqq \textbf{t} \end{array}$	
06	Glass crack	y X	↑ Z	y	*	↑ Z	2.5
		y: Chip width	X:	Chip leng	gth	z: Chip thickness	
		y≦ L		x ≤ 1/8a		$0 < z \le t$	
						over 2/3 of the ITO must terminal specifications.	
						mer, the alignment mark not	
		be damaged.					
		6.2.3 Substrate proto	uberance an	d internal	crack.		
		5		y:	width	x: length	
				y s	≤1/3L	$x \leq a$	
~		X y		•			

No	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
00	Backlight	8.2 Spots or scratched that appear when lit must be judged. Using	2.5
08	elements	LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or	2.5
		contamination.	
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the seal	2.5
		area on the PCB. And there should be no more than three places.	
		10.5 No oxidation or contamination PCB terminals.	
		10.6 Parts on PCB must be the same as on the production	2.5
10	PCB、COB	characteristic chart. There should be no wrong parts, missing	0.65
		parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product	
		characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	
		screw hold pad, make sure it is smoothed down.	2.5
		10.9 The Scraping testing standard for Copper Coating of PCB	
			2.5
		X	
	1	$X * Y \le 2mm^2$	
	A Y	11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections, oxidation	2.5
11	Soldering	or icicle.	
	1/4	11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin	2.5
		(OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin	2.5
		must be present or look as if it cause the interface pin to sever.	
	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

12.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limi	ted value	is set up	accordi	ng to Ro	HS.					

- 2.Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : $235\pm5^{\circ}$ C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



winstar <u>LCM Samp</u> Module Number :		Feedback Sheet Page: 1
1 · Panel Specification :		Tuge. I
1. Panel Type:	Pass	□ NG,
2. View Direction:	Pass	□ NG ,
3. Numbers of Dots:	☐ Pass	□ NG ,
4. View Area:	☐ Pass	□ NG ,
5. Active Area:	Pass	□ NG ,
6. Operating Temperature :	Pass	□ NG ,
7. Storage Temperature :	☐ Pass	□ NG ,
8. Others:		
2 · Mechanical Specification :		
1. PCB Size:	Pass	\square NG,
2. Frame Size:	Pass	□ NG,
3. Materal of Frame:	Pass	□ NG,
4. Connector Position:	☐ Pass	□ NG,
5. Fix Hole Position:	Pass	□ NG,
6. Backlight Position:	☐ Pass	□ NG,
7. Thickness of PCB:	Pass	□ NG ,
8. Height of Frame to PCB:	Pass	□ NG,
9. Height of Module:	Pass	□ NG,
10. Others:	☐ Pass	☐ NG,
3 · Relative Hole Size :		
1. Pitch of Connector:	☐ Pass	□ NG ,
2. Hole size of Connector:	Pass	□ NG ,
3. Mounting Hole size:	☐ Pass	□ NG ,
4. Mounting Hole Type:	Pass	□ NG ,
5. Others:	☐ Pass	□ NG ,
4 · Backlight Specification :		
1. B/L Type:	☐ Pass	□ NG ,
2. B/L Color:	☐ Pass	□ NG ,
3. B/L Driving Voltage (Refere	ence for LED 7	
4. B/L Driving Current:	Pass	□ NG ,
5. Brightness of B/L:	Pass	□ NG ,
6. B/L Solder Method:	Pass	□ NG ,
7. Others:	Pass	□ NG ,
	>> Go to	page 2 <<

oan	le Number :		Page: 2
	Electronic Characteristics of		
	Input Voltage:	Pass	□ NG ,
2.	Supply Current:	☐ Pass	☐ NG ,
3.	Driving Voltage for LCD:	Pass	□ NG ,
4.	Contrast for LCD:	☐ Pass	□ NG ,
5.	B/L Driving Method:	☐ Pass	□ NG ,
6.	Negative Voltage Output:	☐ Pass	□ NG ,
7.		☐ Pass	□ NG ,
8.	LCD Uniformity:	☐ Pass	□ NG ,
9.	ESD test:	Pass	□ NG ,
10.	Others:	☐ Pass	□ NG ,
6、	Summary :		
4			

14.Initial code

```
//WO240128B 2016.06.17 Winstar
//For FSTN White
void initial()
{
    RES=1;
    delay(200);
    RES=0;
    delay(200);
    RES=1;
    delay(200);
    write\_com(0xD7);
                            // Disable Auto Read
    write_dat(0x9F);
    write_com(0xE0);
                            // Enable OTP Read
    write_dat(0x00);
    delay(20);
    write_com(0xE3);
                            // OTP Up-Load
    delay(20);
                            // OTP Control Out
    write_com(0xE1);
                            // Sleep Out
    write\_com(0x11);
                            // Display OFF
    write\_com(0x28);
    delay(50);
    write_com(0xC0);
                                  Vop = 0X11Dh -----
    write_dat(0x1D);
    write_dat(0x01);
                            //
                            // BIAS = 1/12 -----
    write_com(0xC3);
    write_dat(0x02);
                            //
    write_com(0xC4);
                            // Set Booster
    write_dat(0x07);
    write_com(0xD0);
                            // Enable Analog Circuit
    write_dat(0x1D);
```

```
write_com(0xB5);
                          // N-Line = 0; Frame inversion
    write_dat(0x00);
    write\_com(0x39);
                          //Display Mode : Monochrome mode(B/W Mode)
                 FSTN White Temperature Compensation
                          // Frame Rate (Monochrome Mode)
    write_com(0xF1);
    write_dat(0x06);
                          //
                          //
    write_dat(0x0B);
    write_dat(0x0D);
                           //
    write_dat(0x12);
//----
                 FSTN White Temperature Compensation
    write_com(0xF4);
                          //Temperature Gradient Compensation
    write_dat(0x7F);
                          //MT1, MT0
    write_dat(0x22);
                          //MT3, MT2
    write_dat(0x11);
                          //MT5, MT4
    write_dat(0x02);
                          //MT7, MT6
    write_dat(0x00);
                          //MT9, MT8
    write_dat(0x32);
                          //MTB, MTA
                          //MTD, MTC
    write_dat(0x82);
                          //MTF, MTE
    write_dat(0xB6);
//----
    write_com(0x3A);
                          // Enable DDRAM Interface
    write_dat(0x02);
    write_com(0x36);
                          // Scan Direction Setting/Display Control
    write_dat(0x00);
    write_com(0xB0);
                          // Duty Setting -----
    write_dat(0x7F);
                          // 1/128Duty
write\_com(0x20);
                          // Normal display
    write\_com(0x37);
                          // Start Line
    write_dat(0x00);
                          //
    write_com(0xB1);
                          // First Output COM
    write_dat(0x00);
                          //
```

```
write_com(0xB3);
                       //FOSC Divider
write_dat(0x00);
                       //
                       // Column Address Setting
write_com(0x2A);
write_dat(0x00);
write_dat(0x00);
write_dat(0x00);
write_dat(79);
                       //
write_com(0x2B);
                       // Row Address Setting
write_dat(0x00);
write_dat(0x00);
write_dat(0x00);
write_dat(127);
                       //
                       // Display ON
write\_com(0x29);
}
```